Ultra Small Series (0201)



1. INTRODUCTION

MLCC consists of a conducting material and electrodes. To manufacture a chip-type SMT and achieve miniaturization, high density and high efficiency, ceramic condensers are used.

0201 MLCC is performed by high precision technology achieve high capacitance in unit size and ensure the stability and reliability of products.

2. FEATURES

- b. High capacitance in unit size.
- c. High precision dimensional tolerances.
- Suitable used in high-accuracy automatic mounting machine.

3. APPLICATIONS

- a. Miniature microwave module.
- b. Portable equipments (ex. Mobile phone, PDA).
- c. High frequency circuits.

4. HOW TO ORDER

<u>0201</u>	<u>N</u>	<u>100</u>	ī	<u>250</u>	L	Ī
<u>Size</u>	<u>Dielectric</u>	<u>Capacitance</u>	<u>Tolerance</u>	Rated voltage	<u>Termination</u>	<u>Packaging</u>
Inch (mm) 0201 (0603)	N=NP0 (COG) B=X7R X=X5R	Two significant digits followed by no. of zeros. And R is in place of decimal point. eg.: R47=0.47pF 0R5=0.5pF 1R0=1.0pF 100=10x10 ⁰ =10pF	B =±0.1pF	Two significant digits followed by no. of zeros. And R is in place of decimal point. 4R0=4 VDC 6R3=6.3 VDC 100=10 VDC 160=16 VDC 250=25 VDC	L=Ag/Ni/Sn (for NP0 dielectric) C=Cu/Ni/Sn (for X7R, X5R & Y5V dielectric)	T=7" reeled
				500 =50 VDC		

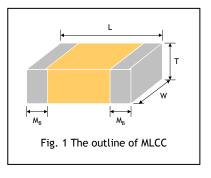
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5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	T (mm)/Symbol		M _B (mm)
0201 (0603)	0.60±0.03	0.30±0.03	0.30±0.03	L	0.15±0.05

^{*} Reflow soldering only.



6. GENERAL ELECTRICAL DATA

Size		0201				
Dielectric	NP0	X7R	X5R			
Capacitance*	Capacitance* 0.5pF to 100pF		100pF to 0.10μF			
Capacitance tolerance**	Cap≤5pF: B (±0.1pF), C (±0.25pF) 5pF <cap<10pf: (±0.25pf),d(±0.5pf)<br="" c="">Cap≥10pF: F (±1%), G (±2%), J (±5%),</cap<10pf:>	J (±5%), K (±10%), M (±20%)	J (±5%),K (±10%), M (±20%)			
	K (±10%)					
Rated voltage (WVDC)	16V, 25V	10V, 16V, 25V, 50V	6.3V,10V, 16V,25V,50V			
	Cap < 20pE 0>400 / 20C	Ur=50V: ≤3.0%	Ur=16V: ≤3.5%			
Tan δ / Q*	Cap<30pF, Q≥400+20C	Ur=16V, 25V: ≤3.5%	Ur=10V: ≤5.0%			
	Cap≥30pF, Q≥1000	Ur=10V: ≤5.0%	Ur=6.3V: ≤10%			
Insulation resistance at Ur	≥10 G Ω	≥10GΩ or RxC≥500ΩxF whichever is less				
Operating temperature	-55 to +1	-125°C -55 to +85°C				
Capacitance change	±30ppm	±	15%			
Termination		Ni/Sn (lead-free termination)				

^{*} Measured at 30~70% related humidity.

NPO: Apply $1.0\pm0.2 Vrms$, $1.0 MHz\pm10\%$ at the condition of $25\,^{\circ}C$ ambient temperature.

X7R, X5R: Apply 1.0 \pm 0.2Vrms, 1.0kHz \pm 10% at the condition of 25 $^{\circ}$ C ambient temperature.

^{**} Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in ambient condition for 24±2 hours before measurement.

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7. CAPACITANCE RANGE

	SIZE	02	201
	DIELECTRIC	N	P0
RA	TED VOLTAGE (VDC)	16 25	
	0.5pF (0R5)		Г
	1.0pF (1R0)		L
	1.2pF (1R2)		L
	1.5pF (1R5)		L
	1.8pF (1R8)		L
	2.2pF (2R2)		L
	2.7pF (2R7)		L
	3.0pF (3R0)		L
	3.3pF (3R3)		L
	3.9pF (3R9)		L
	4.0pF(4R0)		L
a,	4.7pF (4R7)		L
Capacitance	5.6pF (5R6)		L
ita	6.8pF (6R8)		L
рас	8.2pF (8R2)		L
ပ္မ	10pF (100)		L
	12pF (120)		L
	15pF (150)		L
	18pF (180)		L
	22pF (220)		L
	27pF (270)		L
	33pF (330)		L
	39pF (390)		L
	47pF (470)		L
	56pF (560)	L	L
	68pF (680)	L	L
	82pF (820)		L
	100pF (101)	L	L

	SIZE				0	201				
DIELECTRIC		X7R				X5R				
RAT	ED VOLTAGE (VDC)	10V	16V	25V	50V	6.3V	10V	16	25	50
	100pF (101)		L	L	L			L	L	L
	120pF (121)		L	L	L			L	L	L
	150pF (151)		L	L	L			L	L	L
	180pF (181)		L	L	L			L	L	L
	220pF (221)		L	L	L			L	L	L
	270pF (271)		L	L	L			L	L	L
	330pF (331)		L	L	L			L	L	L
	390pF (391)		L	L	L			L	L	L
	470pF (471)		L	L	L			L	L	L
	560pF (561)		L	L	L			L	L	L
မ	680pF (681)		L	L	L			L	L	L
anc	820pF (821)		L	L	L			L	L	L
Capacitance	1,000pF (102)		L	L	L			L	L	L
аре	1,500pF (152)	L	L				L	L		
J	2,200pF (222)	L	L				L	L		
	3,300pF (332)	L	L				L	L		
	4,700pF (472)	L	L				L	L		
	6,800pF (682)	L				ļ	L			
	0.010µF (103)	L					L			
	0.015µF (153)					L				
	0.022µF (223)					L				
	0.033µF (333)					L				
	0.047µF (473)					L				
	0.068µF (683)					L				
	0.10µF (104)					L				

1. The letter in cell is expressed the symbol of product thickness.

8. PACKAGING DIMENSION AND QUANTITY

Size	Thiskness (mm) (Sumbal		Paper	Paper tape		
Size	Thickness (mm)/Symbo	Л	7" reel	13" reel		
0201 (0603)	0.30±0.03	L	15K	-		

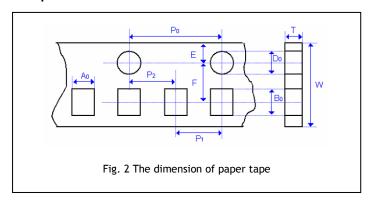
Unit: pieces

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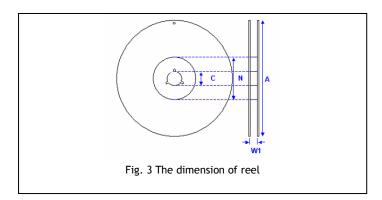


9. APPENDIXES

■ Tape & reel dimensions

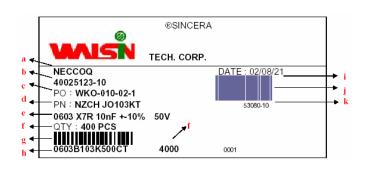


Size	0201
Thickness	L
A_0	0.37 ±0.03
Bo	0.67 ±0.03
T	0.42 ±0.03
K _o	-
W	8.00 ±0.10
P_0	4.00 ±0.10
10xP ₀	40.0 ±0.10
P ₁	2.00 ±0.05
P ₂	2.00 ±0.05
D_0	1.55 ±0.05
D_1	-
E	1.75 ±0.05
F	3.50 ±0.05



Size	0201					
Reel size	7"	13"				
С	13.0+0.5/-0.2	13.0+0.5/-0.2				
W ₁	8.4+1.5/-0	8.4+1.5/-0				
Α	178.0 ±0.10	330.0±1.0				
N	60.5 ±1.0	100 ±1.0				

■ Description of customer label



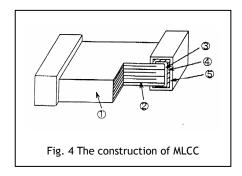
- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label

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Constructions

No.	Nam	ne	NP0	X7R, X5R, Y5V	
1	Ceramic n	naterial	BaTiO₃ based		
2	Inner ele	ctrode	AgPd alloy	Ni	
3		Inner layer	Ag	Cu	
4	Termination	Middle layer	Ni		
(5)		Outer layer	9	in (Matt)	



■ Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering.
- b. To store products on the shelf and avoid exposure to moisture.
- c. Don't expose products to excessive shock, vibration, direct sunlight and so on.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N_2 within oven are recommended.

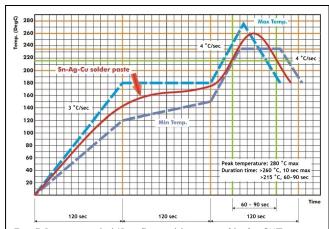


Fig. 5 Recommended IR reflow soldering profile for SMT process with SnAgCu series solder paste.

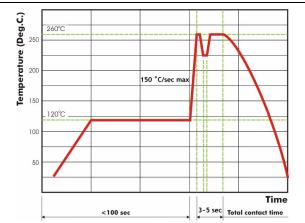


Fig. 6 Recommended wave soldering profile for SMT process with SnAgCu series solder.